

V_{CES}	1200V
I_C	49A
$V_{CE(sat)}$ (Typ.)	1.60V
P_D	348W

●Features

- 1) Qualified to AEC-Q101
- 2) Short Circuit Withstand Time 10 μ s
- 3) Low Collector - Emitter Saturation Voltage
- 4) Built in Very Fast & Soft Recovery FRD
- 5) Pb - free Lead Plating ; RoHS Compliant

●Application

General Inverter

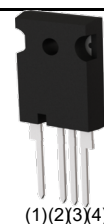
for Automotive and Industrial Use

HV Heater

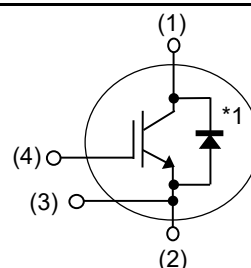
Relay Circuit (ex. Pre Charge Relay)

●Outline

TO-247-4L



●Inner Circuit



- (1) Collector
- (2) Power Emitter
- (3) Kelvin Emitter
- (4) Gate

*1 Built in FRD

●Packaging Specifications

Type	Packaging	Tube
	Reel Size (mm)	-
	Tape Width (mm)	-
	Basic Ordering Unit (pcs)	450
	Packing Code	C15
	Marking	RG A50TRX2E

●Absolute Maximum Ratings (at $T_C = 25^\circ\text{C}$ unless otherwise specified)

Parameter		Symbol	Value	Unit
Collector - Emitter Voltage		V_{CES}	1200	V
Gate - Emitter Voltage		V_{GES}^{*1}	± 30	V
Collector Current	$T_C = 25^\circ\text{C}$	I_C	74	A
	$T_C = 100^\circ\text{C}$	I_C	49	A
Pulsed Collector Current		I_{CP}^{*2}	75	A
Diode Forward Current	$T_C = 25^\circ\text{C}$	I_F	63	A
	$T_C = 100^\circ\text{C}$	I_F	39	A
Diode Pulsed Forward Current		I_{FP}^{*2}	75	A
Power Dissipation	$T_C = 25^\circ\text{C}$	P_D	348	W
	$T_C = 100^\circ\text{C}$	P_D	174	W
Operating Junction Temperature		T_j	-40 to +175	$^\circ\text{C}$
Storage Temperature		T_{stg}	-55 to +175	$^\circ\text{C}$

*1 Please be advised not to use IGBTs with V_{GE} below 10V as doing so may cause thermal runaway.

*2 Pulse width limited by T_{jmax} .

●Thermal Resistance

Parameter	Symbol	Values			Unit
		Min.	Typ.	Max.	
Thermal Resistance IGBT Junction - Case	$R_{\theta(j-c)}$	-	-	0.43	°C/W
Thermal Resistance Diode Junction - Case	$R_{\theta(j-c)}$	-	-	0.80	°C/W

●IGBT Electrical Characteristics (at $T_j = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Collector - Emitter Breakdown Voltage	BV_{CES}	$I_C = 10\mu\text{A}$, $V_{GE} = 0\text{V}$	1200	-	-	V
Collector Cut - off Current	I_{CES}	$V_{CE} = 1200\text{V}$, $V_{GE} = 0\text{V}$, $T_j = 25^\circ\text{C}$	-	-	10	μA
		$T_j = 175^\circ\text{C}$	-	400	-	μA
Gate - Emitter Leakage Current	I_{GES}	$V_{GE} = \pm 30\text{V}$, $V_{CE} = 0\text{V}$	-	-	± 500	nA
Gate - Emitter Threshold Voltage	$V_{GE(th)}$	$V_{CE} = 5\text{V}$, $I_C = 3.1\text{mA}$	5.0	5.8	6.6	V
Collector - Emitter Saturation Voltage	$V_{CE(sat)}$	$I_C = 25\text{A}$, $V_{GE} = 15\text{V}$, $T_j = 25^\circ\text{C}$	-	1.60	2.00	V
		$T_j = 175^\circ\text{C}$	-	2.15	-	V

●IGBT Electrical Characteristics (at $T_j = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Input Capacitance	C_{ies}	$V_{CE} = 30\text{V}$, $V_{GE} = 0\text{V}$, $f = 1\text{MHz}$	-	4358	-	pF
Output Capacitance	C_{oes}		-	136	-	
Reverse transfer Capacitance	C_{res}		-	35	-	
Total Gate Charge	Q_g	$V_{CE} = 800\text{V}$, $I_C = 25\text{A}$, $V_{GE} = 15\text{V}$	-	163	-	nC
Gate - Emitter Charge	Q_{ge}		-	30	-	
Gate - Collector Charge	Q_{gc}		-	75	-	
Turn - on Delay Time	$t_{d(on)}$	$I_C = 25\text{A}$, $V_{CC} = 800\text{V}$, $V_{GE} = 15\text{V}$, $R_G = 10\Omega$, $T_j = 25^\circ\text{C}$ Inductive Load *Eon does not include diode reverse recovery	-	52	-	ns
Rise Time	t_r		-	13	-	
Turn - off Delay Time	$t_{d(off)}$		-	255	-	
Fall Time	t_f		-	205	-	
Turn-on Switching Loss	E_{on}		-	0.28	-	mJ
Turn-off Switching Loss	E_{off}		-	1.98	-	
Turn - on Delay Time	$t_{d(on)}$	$I_C = 25\text{A}$, $V_{CC} = 800\text{V}$, $V_{GE} = 15\text{V}$, $R_G = 10\Omega$, $T_j = 175^\circ\text{C}$ Inductive Load *Eon does not include diode reverse recovery	-	53	-	ns
Rise Time	t_r		-	18	-	
Turn - off Delay Time	$t_{d(off)}$		-	249	-	
Fall Time	t_f		-	265	-	
Turn-on Switching Loss	E_{on}		-	0.38	-	mJ
Turn-off Switching Loss	E_{off}		-	2.59	-	
Reverse Bias Safe Operating Area	$\begin{matrix} *3 \\ \text{RBSOA} \end{matrix}$	$I_C = 75\text{A}$, $V_{CC} = 1050\text{V}$, $V_p = 1200\text{V}$, $V_{GE} = 15\text{V}$, $R_G = 50\Omega$, $T_j = 175^\circ\text{C}$	FULL SQUARE			-
Short Circuit Withstand Time	t_{sc}	$V_{CC} \leq 800\text{V}$, $V_{GE} = 15\text{V}$, $T_j = 25^\circ\text{C}$	10	-	-	μs
Short Circuit Withstand Time	t_{sc}^{*3}	$V_{CC} \leq 800\text{V}$, $V_{GE} = 15\text{V}$, $T_j = 150^\circ\text{C}$	8	-	-	μs

*3 Design assurance without measurement

●FRD Electrical Characteristics (at $T_j = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Diode Forward Voltage	V_F	$I_F = 25\text{A}$, $T_j = 25^\circ\text{C}$ $T_j = 175^\circ\text{C}$	- -	1.65 1.85	2.10 -	V
Diode Reverse Recovery Time	t_{rr}	$I_F = 25\text{A}$, $V_{CC} = 800\text{V}$, $di_F/dt = 500\text{A}/\mu\text{s}$, $T_j = 25^\circ\text{C}$	-	326	-	ns
Diode Peak Reverse Recovery Current	I_{rr}		-	15.9	-	A
Diode Reverse Recovery Charge	Q_{rr}		-	2.8	-	μC
Diode Reverse Recovery Energy	E_{rr}		-	1.3	-	mJ
Diode Reverse Recovery Time	t_{rr}	$I_F = 25\text{A}$, $V_{CC} = 800\text{V}$, $di_F/dt = 500\text{A}/\mu\text{s}$, $T_j = 175^\circ\text{C}$	-	460	-	ns
Diode Peak Reverse Recovery Current	I_{rr}		-	20.0	-	A
Diode Reverse Recovery Charge	Q_{rr}		-	5.0	-	μC
Diode Reverse Recovery Energy	E_{rr}		-	2.5	-	mJ

●Electrical Characteristic Curves

Fig.1 Power Dissipation
vs. Case Temperature

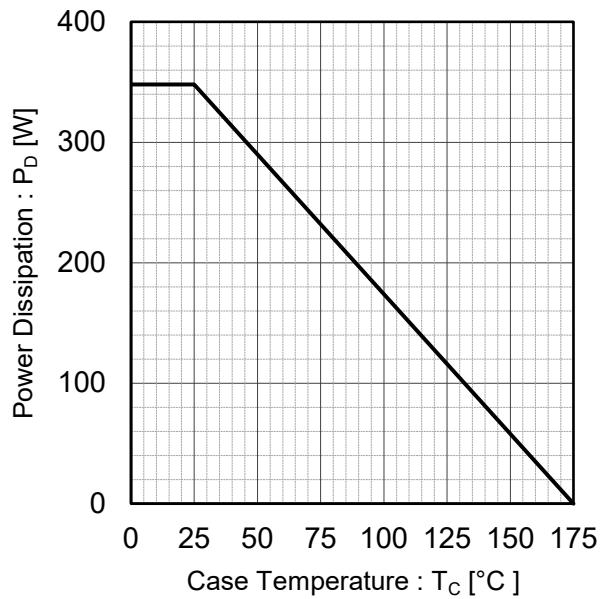


Fig.2 Collector Current
vs. Case Temperature

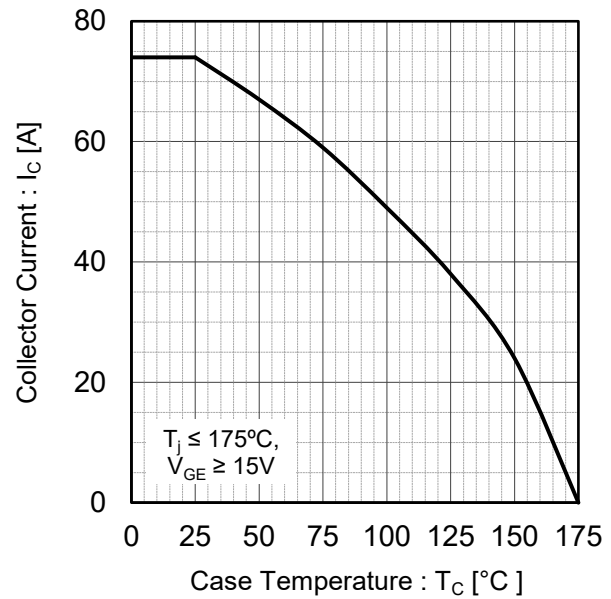


Fig.3 Forward Bias Safe Operating Area

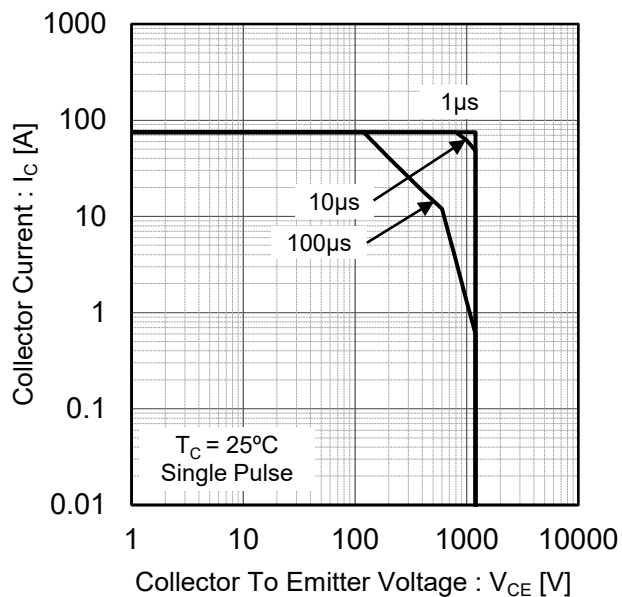
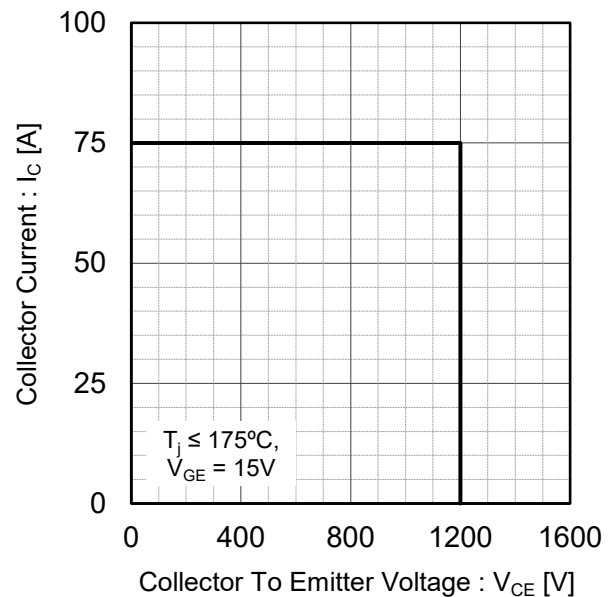


Fig.4 Reverse Bias Safe Operating Area



●Electrical Characteristic Curves

Fig.5 Typical Output Characteristics

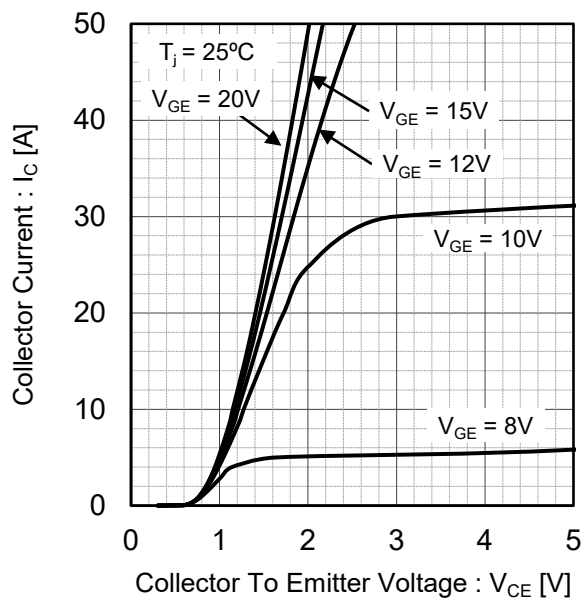


Fig.6 Typical Output Characteristics

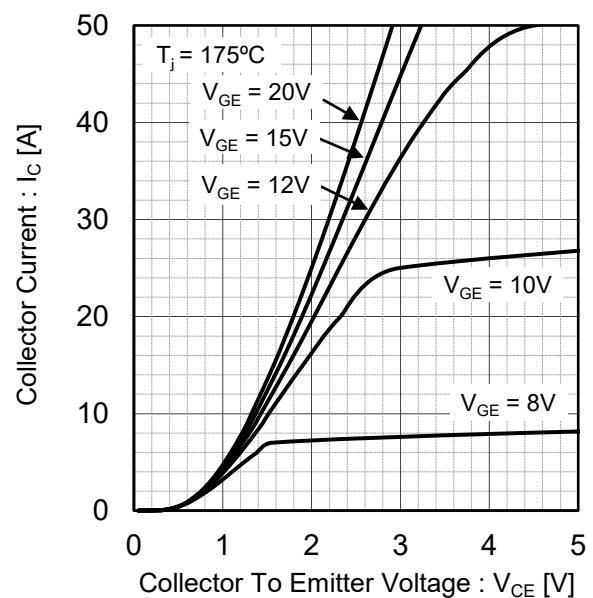


Fig.7 Typical Transfer Characteristics

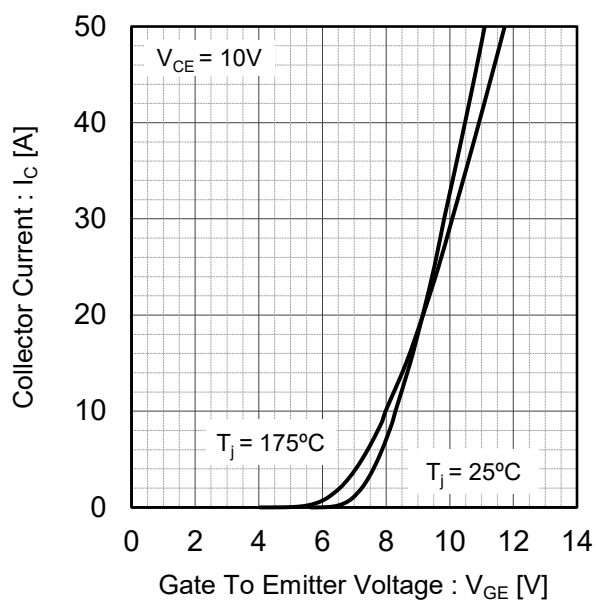
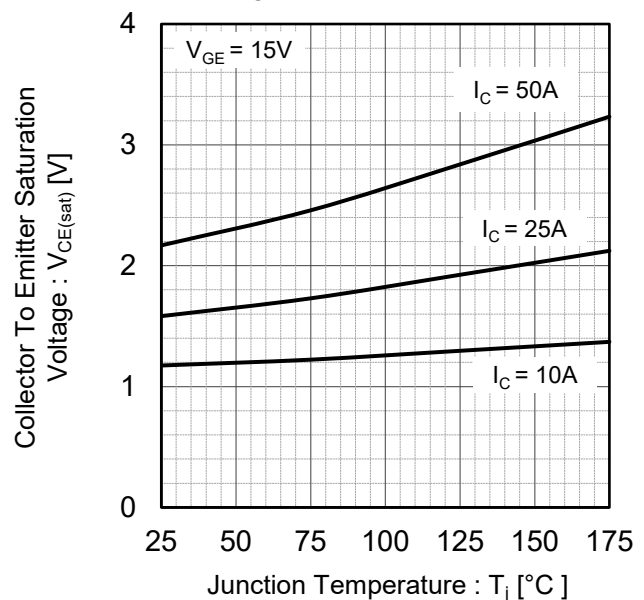


Fig.8 Typical Collector To Emitter Saturation Voltage vs. Junction Temperature



●Electrical Characteristic Curves

Fig.9 Typical Collector To Emitter Saturation Voltage vs. Gate To Emitter Voltage

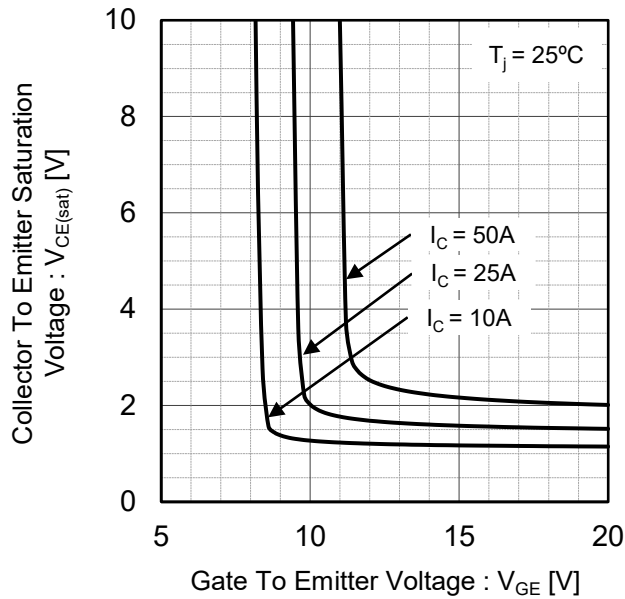


Fig.10 Typical Collector To Emitter Saturation Voltage vs. Gate To Emitter Voltage

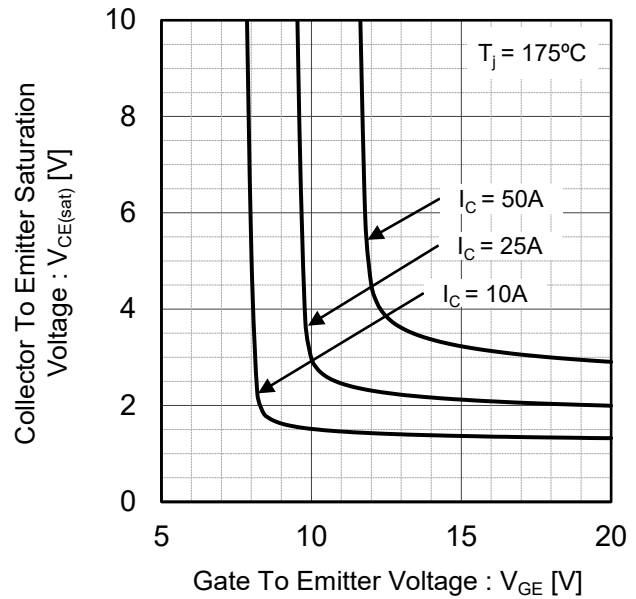


Fig.11 Typical Capacitance vs. Collector To Emitter Voltage

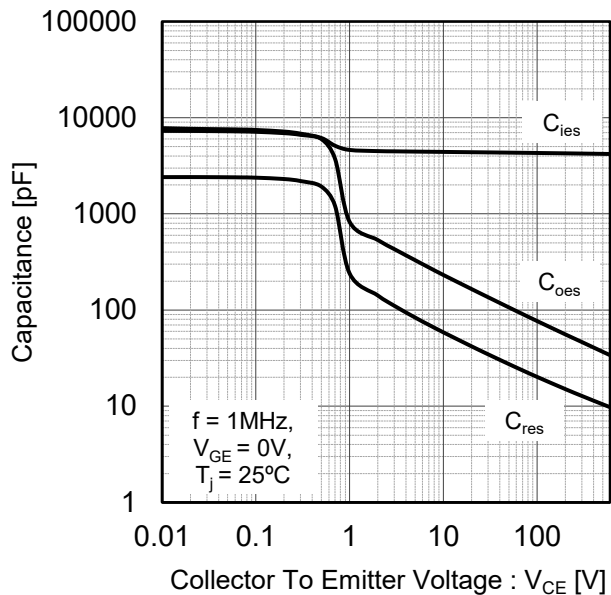
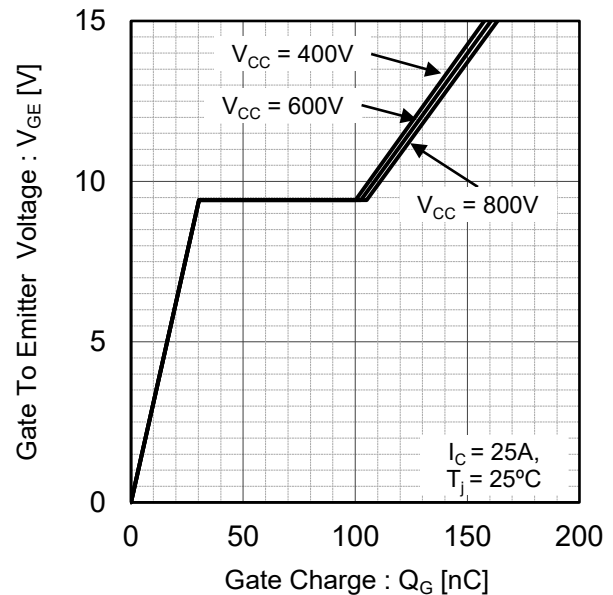


Fig.12 Typical Gate Charge



●Electrical Characteristic Curves

Fig.13 Typical Switching Time
vs. Collector Current

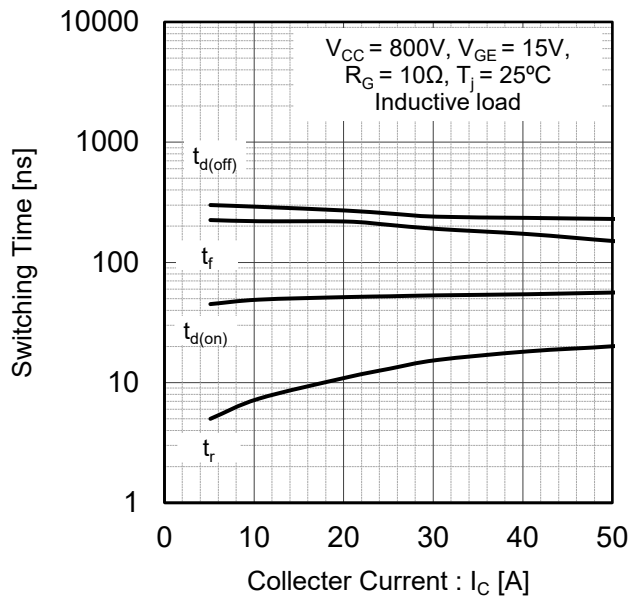


Fig.14 Typical Switching Time
vs. Gate Resistance

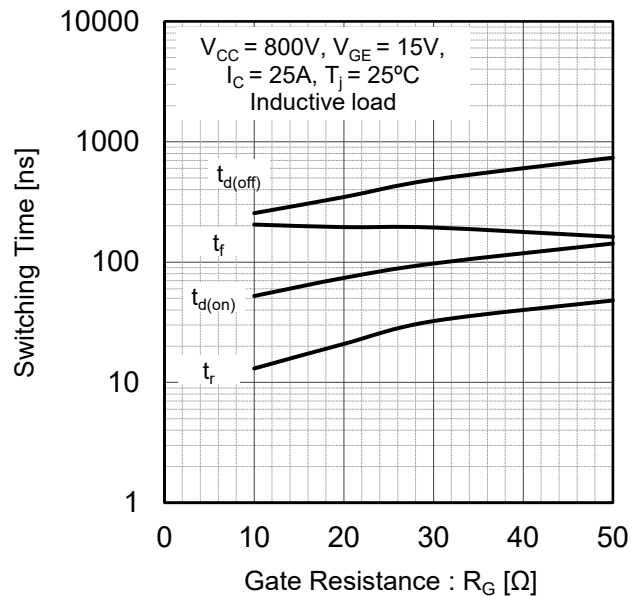


Fig.15 Typical Switching Energy Losses
vs. Collector Current

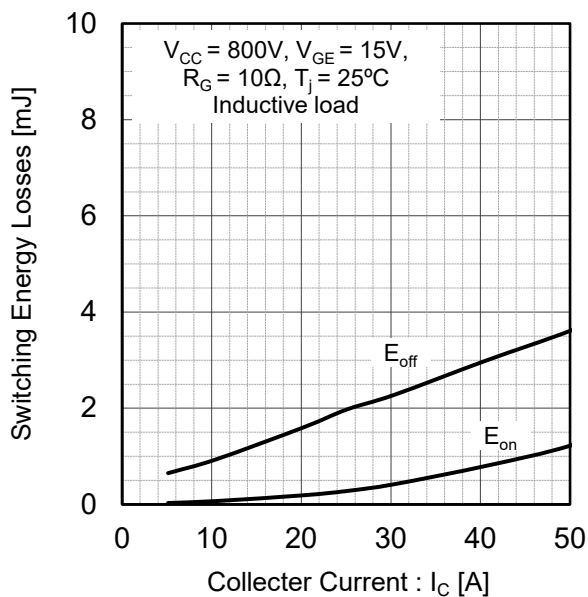
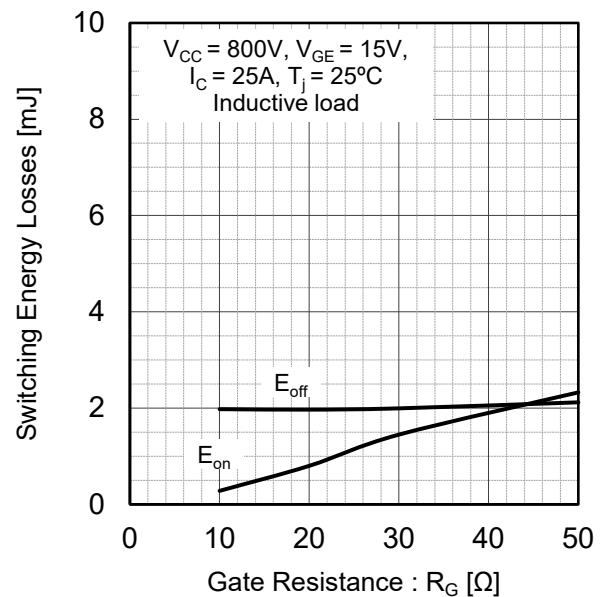


Fig.16 Typical Switching Energy Losses
vs. Gate Resistance



●Electrical Characteristic Curves

Fig.17 Typical Switching Time
vs. Collector Current

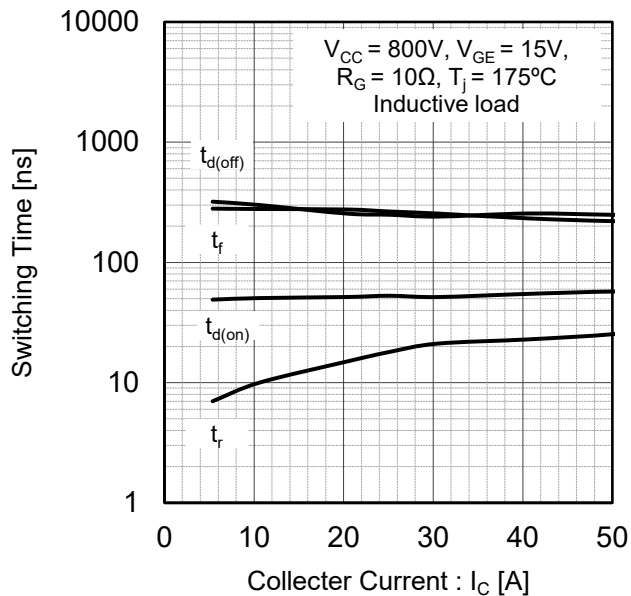


Fig.18 Typical Switching Time
vs. Gate Resistance

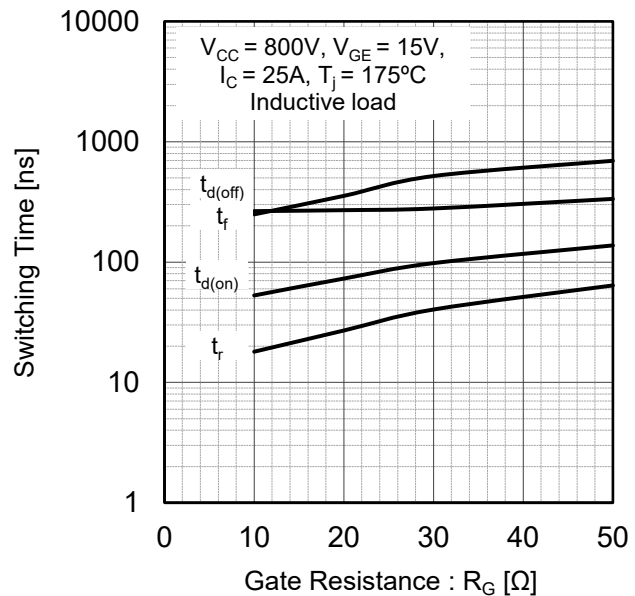


Fig.19 Typical Switching Energy Losses
vs. Collector Current

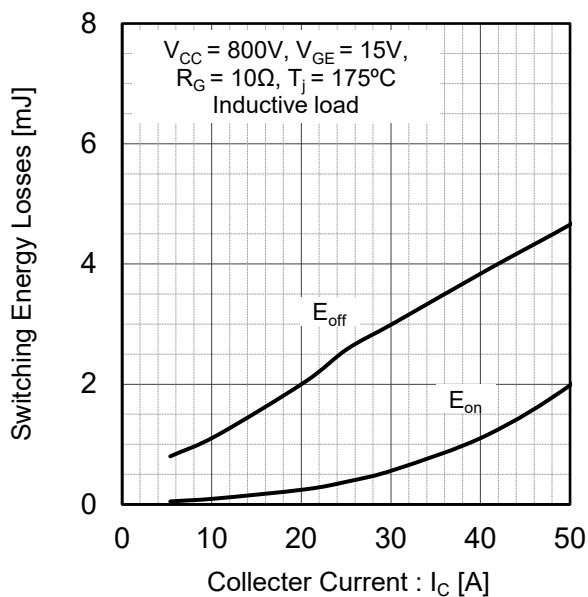
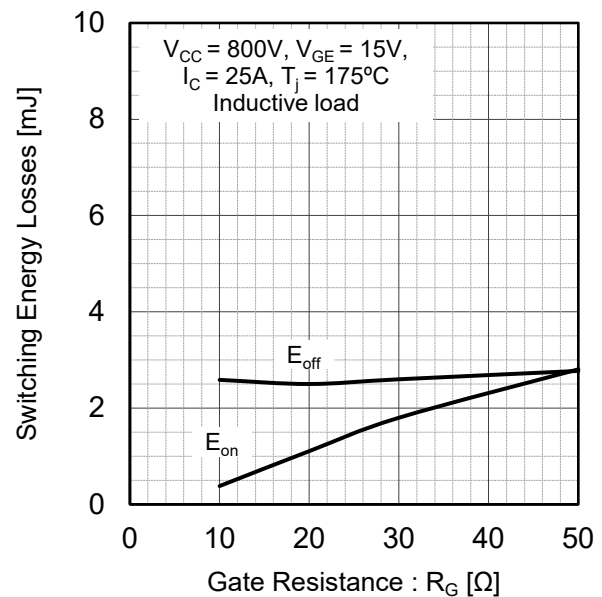


Fig.20 Typical Switching Energy Losses
vs. Gate Resistance



●Electrical Characteristic Curves

Fig.21 Typical Diode Forward Current vs. Forward Voltage

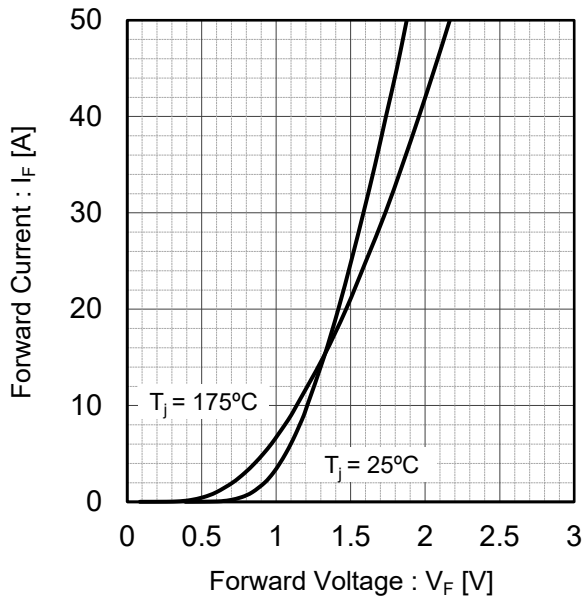


Fig.22 Typical Diode Reverse Recovery Time vs. Forward Current

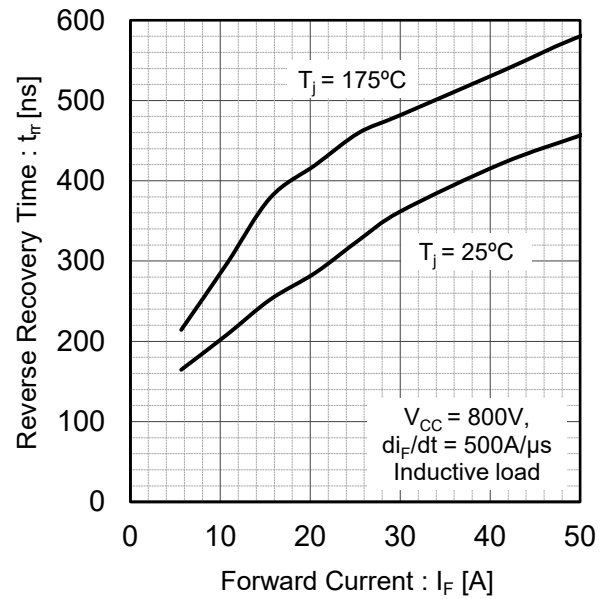


Fig.23 Typical Diode Reverse Recovery Current vs. Forward Current

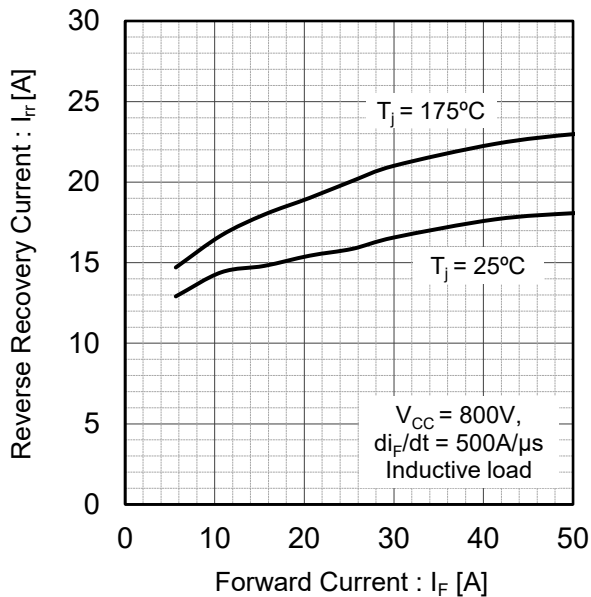
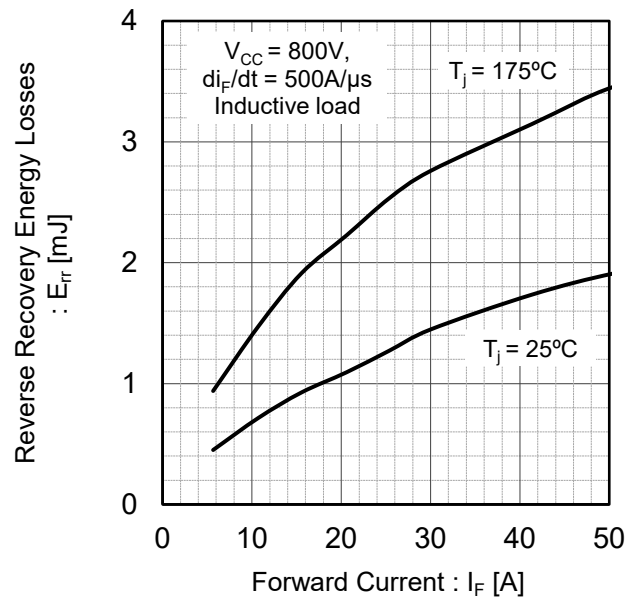


Fig.24 Typical Diode Reverse Recovery Energy Losses vs. Forward Current



●Electrical Characteristic Curves

Fig.25 Typical IGBT Transient Thermal Impedance

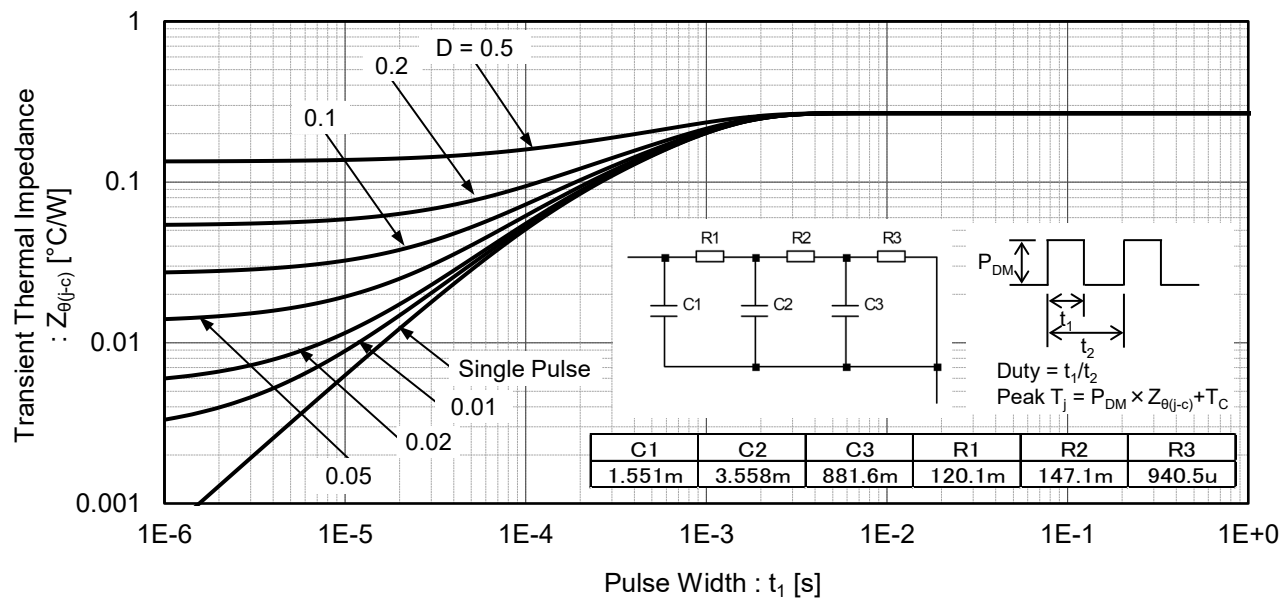
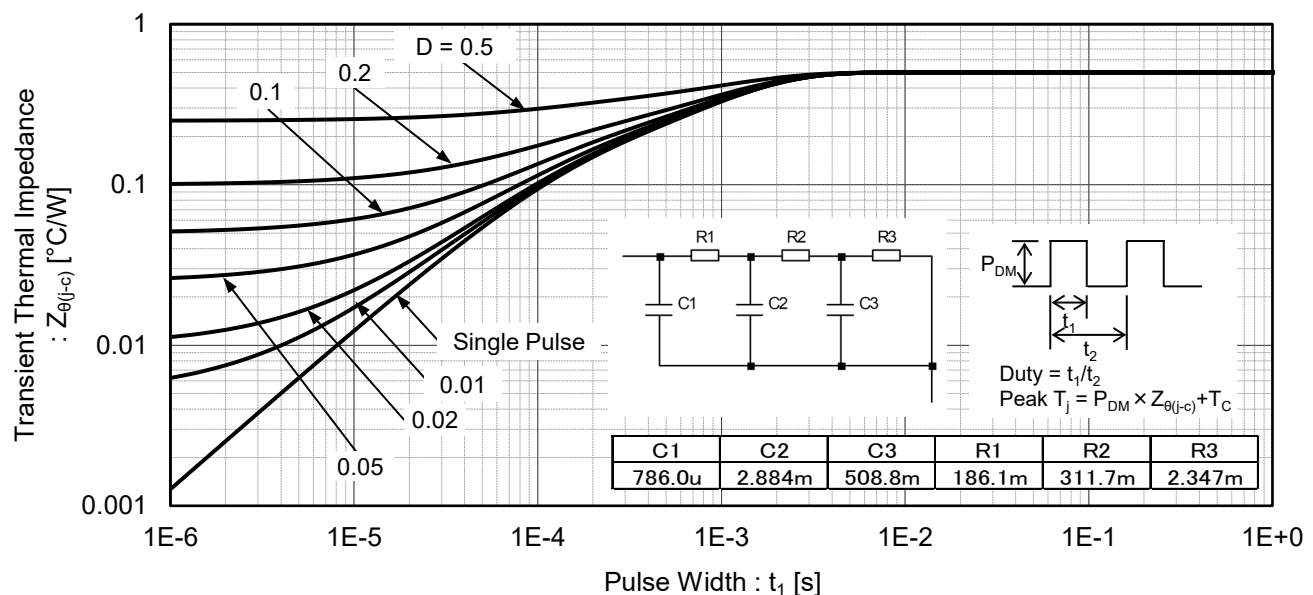


Fig.26 Typical Diode Transient Thermal Impedance



Inductive Load Switching Circuit and Waveform and Short Circuit

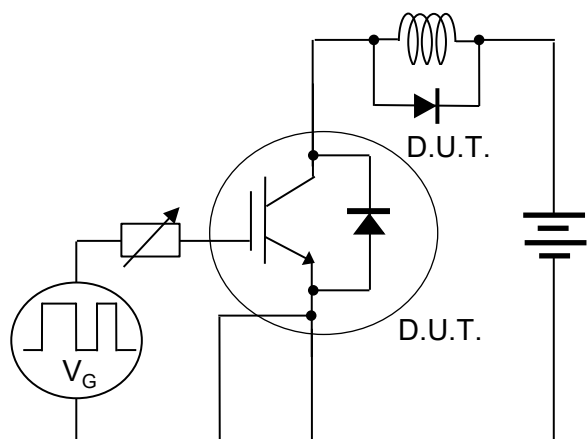


Fig.27 Inductive Load Circuit

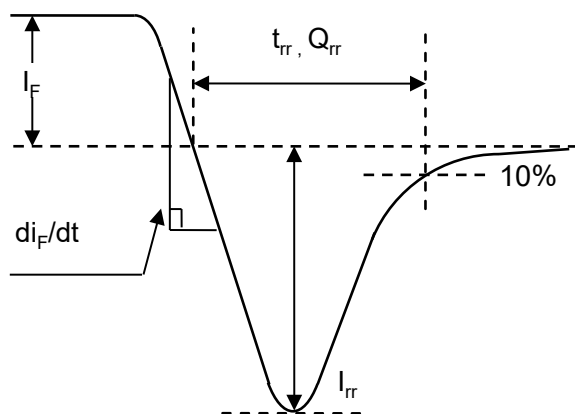


Fig.28 Diode Reverse Recovery Waveform

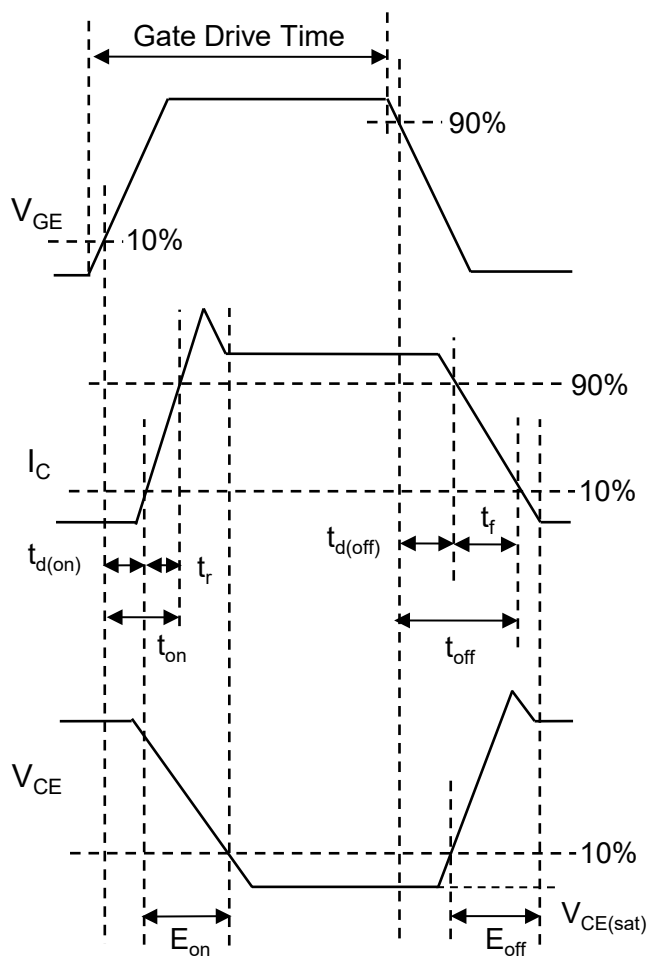


Fig.29 Inductive Load Waveform

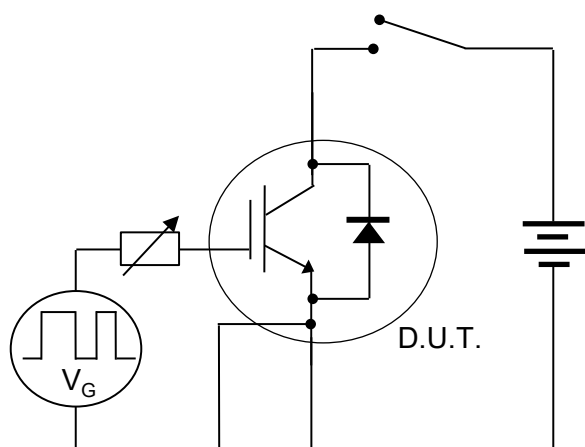


Fig.30 Short Circuit

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